

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: R. IKEZAWA, et al.
Application No.: 10/552,441
Filed: OCTOBER 7, 2005
For: ENCAPSULATING EPOXY RESIN MOLDING MATERIAL, AND
SEMICONDUCTOR DEVICE
Group AU: 2815
Examiner: Jasmine Jhihan B. Clark
Confirm. No.: 7255

AMENDMENT AFTER FINAL REJECTION

Mail Stop: AF – NO FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

January 18, 2008

Sir:

In response to the Office Action mailed October 18, 2007, please amend the
above-identified application as listed in the following, and as set forth on the
following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.

OK to enter
ybc
2/4/8